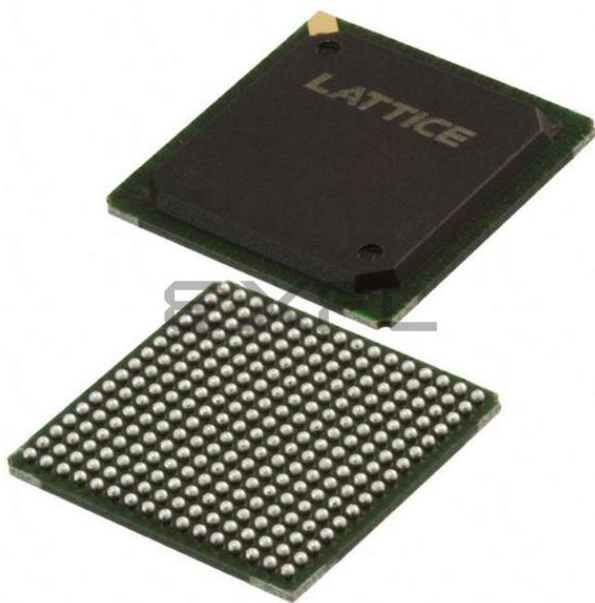




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	384
Number of Gates	-
Number of I/O	192
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-384-192-12fac

Table 4. Architectural Summary of ispMACH 4A devices

	ispMACH 4A Devices	
	M4A3-64/32, M4A5-64/32 M4A3-96/48, M4A5-96/48 M4A3-128/64, M4A5-128/64 M4A3-192/96, M4A5-192/96 M4A3-256/128, M4A5-256/128 M4A3-384 M4A3-512	M4A3-32/32 M4A5-32/32 M4A3-64/64 M4A3-256/160 M4A3-256/192
Macrocell-I/O Cell Ratio	2:1	1:1
Input Switch Matrix	Yes	Yes ¹
Input Registers	Yes	No
Central Switch Matrix	Yes	Yes
Output Switch Matrix	Yes	Yes

The Macrocell-I/O cell ratio is defined as the number of macrocells versus the number of I/O cells internally in a PAL block (Table 4).

The central switch matrix takes all dedicated inputs and signals from the input switch matrices and routes them as needed to the PAL blocks. Feedback signals that return to the same PAL block still must go through the central switch matrix. This mechanism ensures that PAL blocks in ispMACH 4A devices communicate with each other with consistent, predictable delays.

The central switch matrix makes a ispMACH 4A device more advanced than simply several PAL devices on a single chip. It allows the designer to think of the device not as a collection of blocks, but as a single programmable device; the software partitions the design into PAL blocks through the central switch matrix so that the designer does not have to be concerned with the internal architecture of the device.

Each PAL block consists of:

- ◆ Product-term array
- ◆ Logic allocator
- ◆ Macrocells
- ◆ Output switch matrix
- ◆ I/O cells
- ◆ Input switch matrix
- ◆ Clock generator

Notes:

1. M4A3-64/64 internal switch matrix functionality embedded in central switch matrix.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	$\overline{Q}$
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

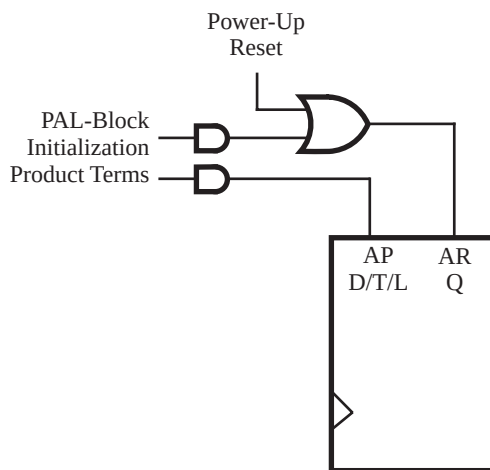
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

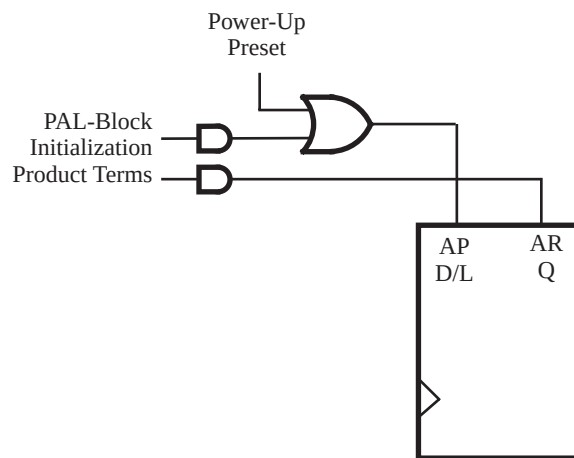
The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset

17466G-012



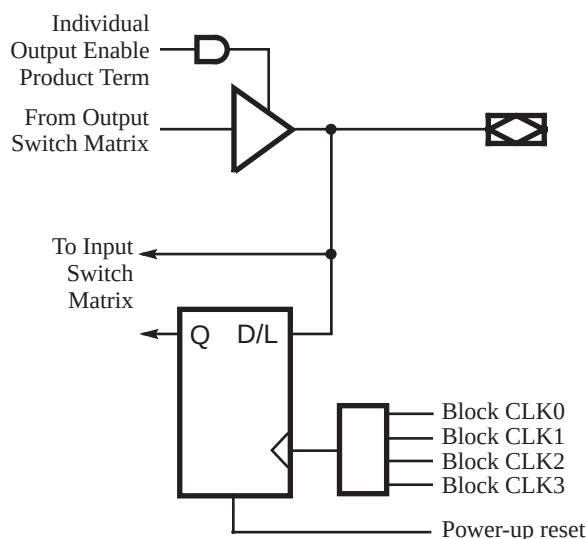
b. Power-up preset

17466G-013

Figure 7. Synchronous Mode Initialization Configurations

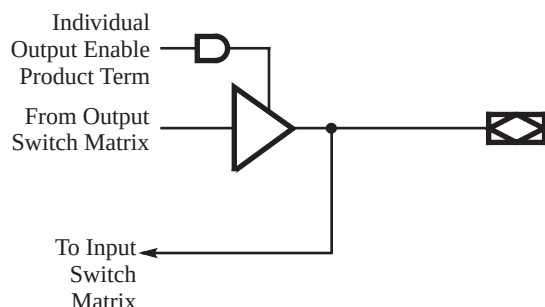
I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.



17466G-017

Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio



17466G-018

Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as “time-domain-multiplexed” data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

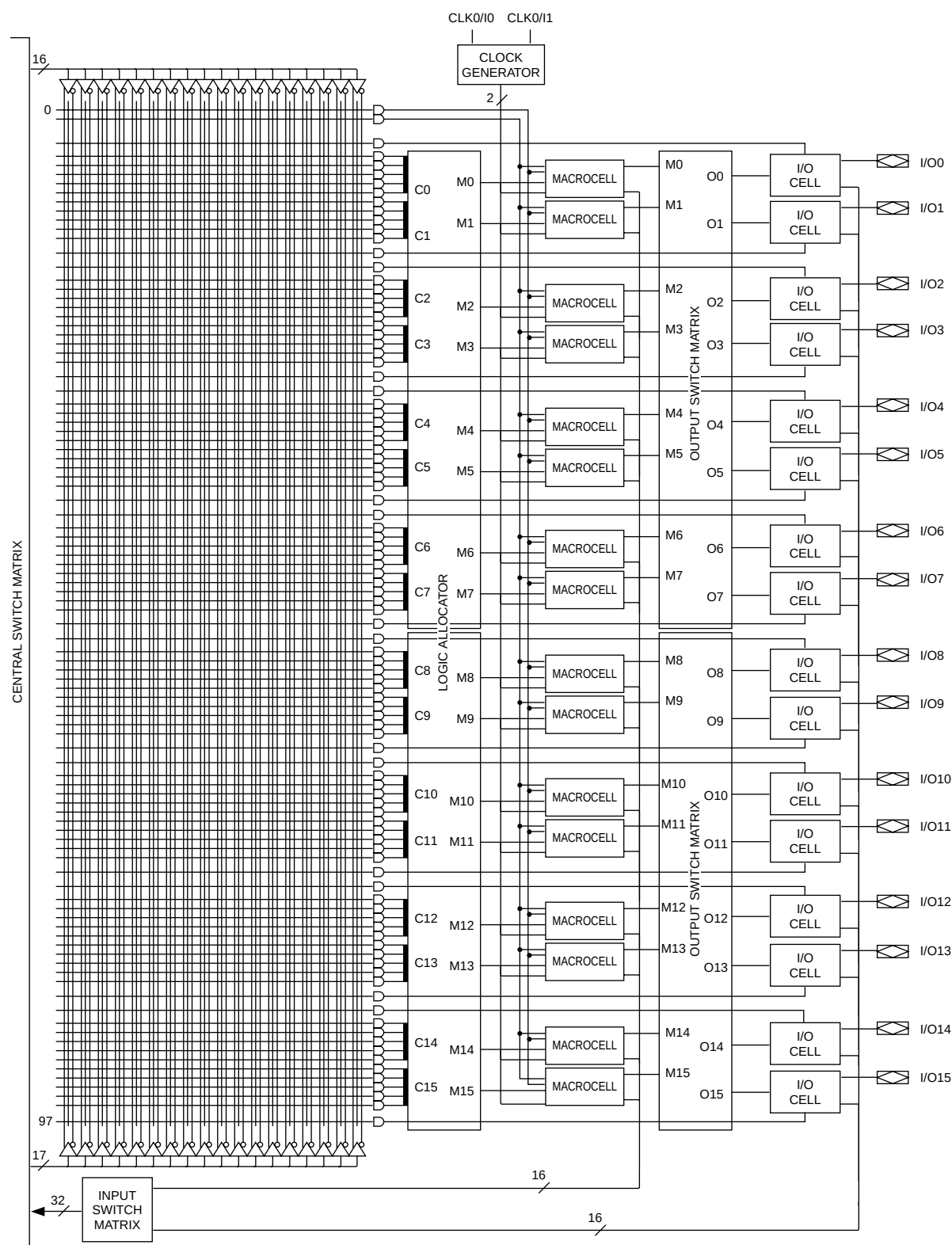
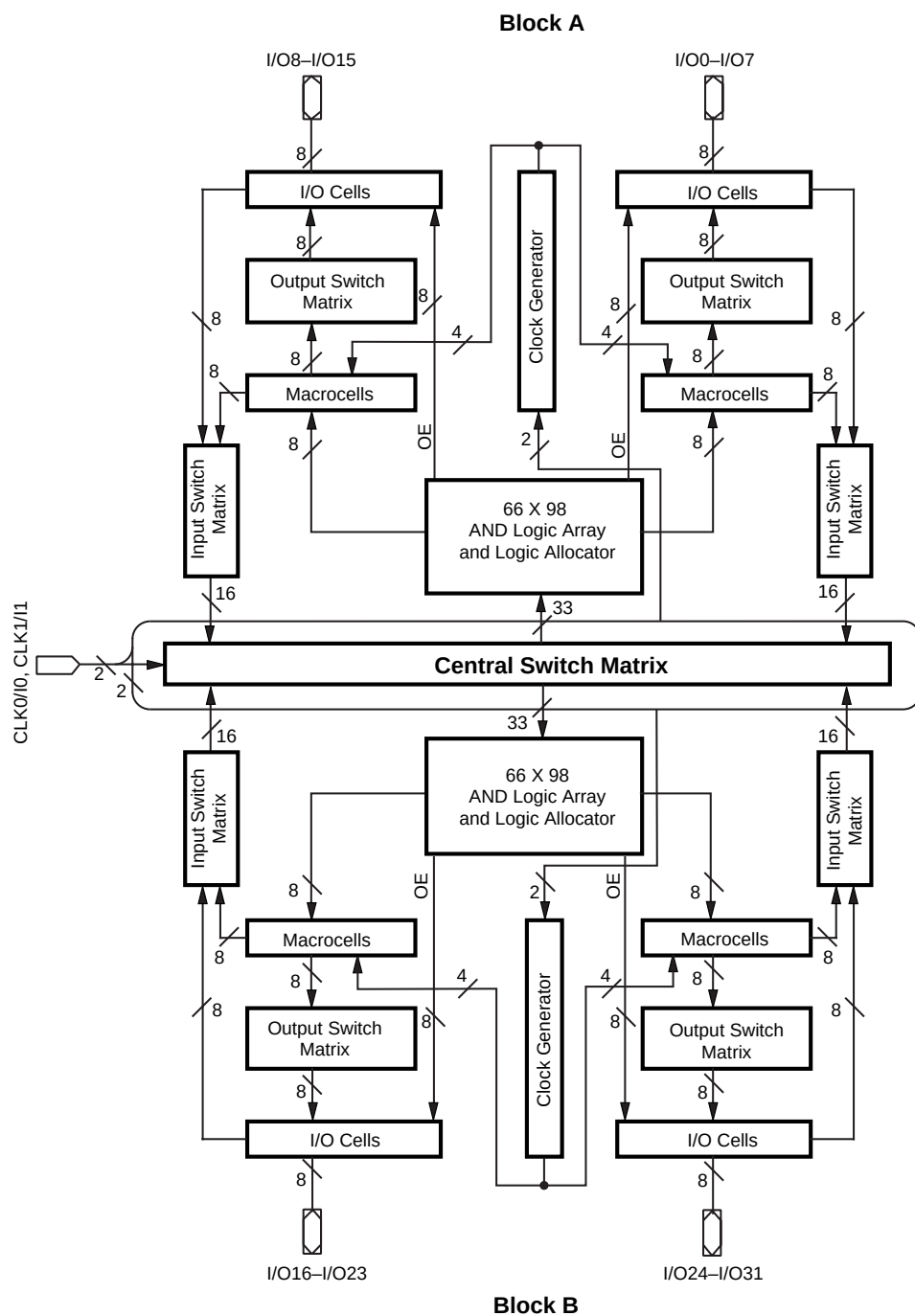


Figure 18. PAL Block for M4A (3,5)-32/32

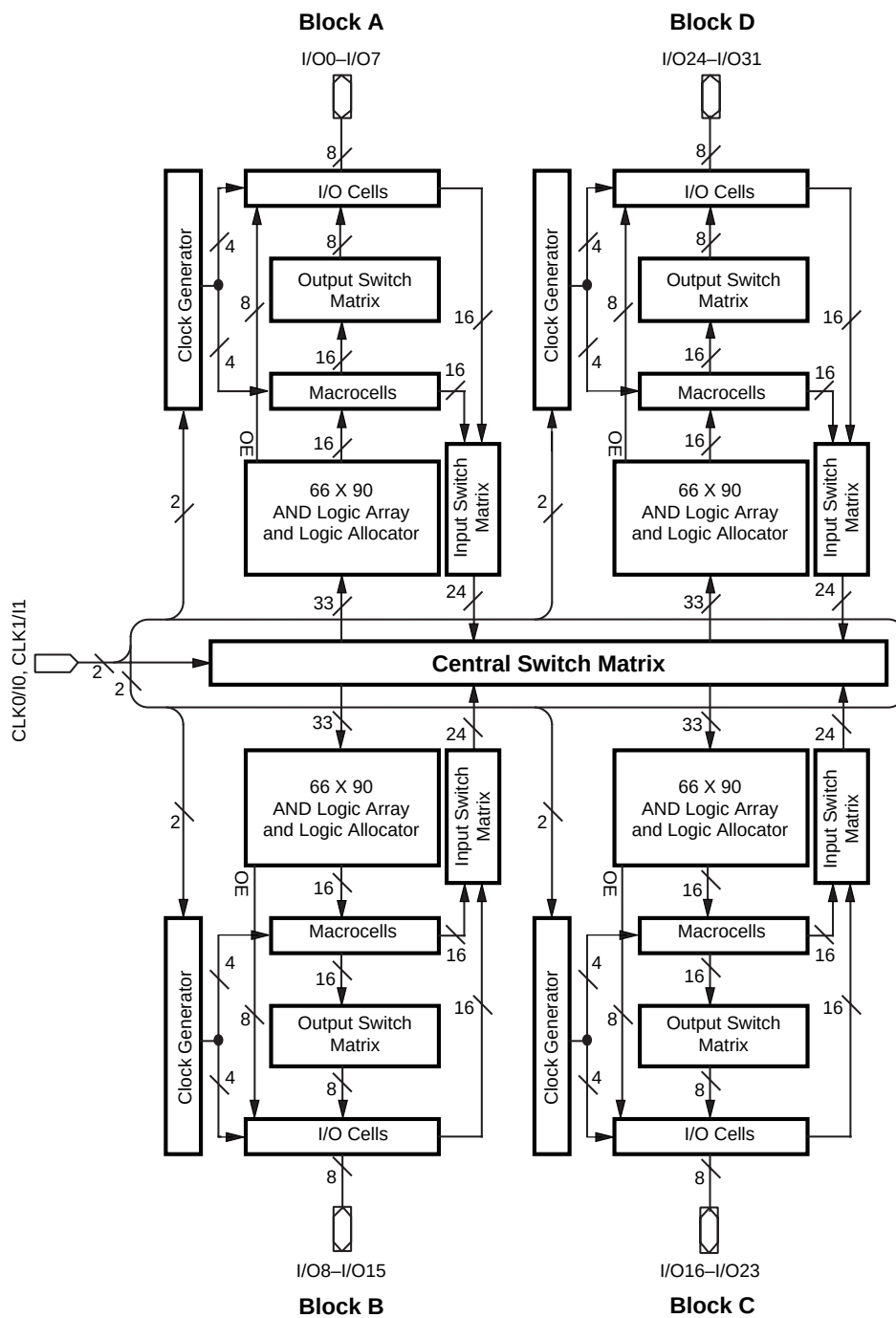
17466H-042

BLOCK DIAGRAM – M4A(3,5)-32/32



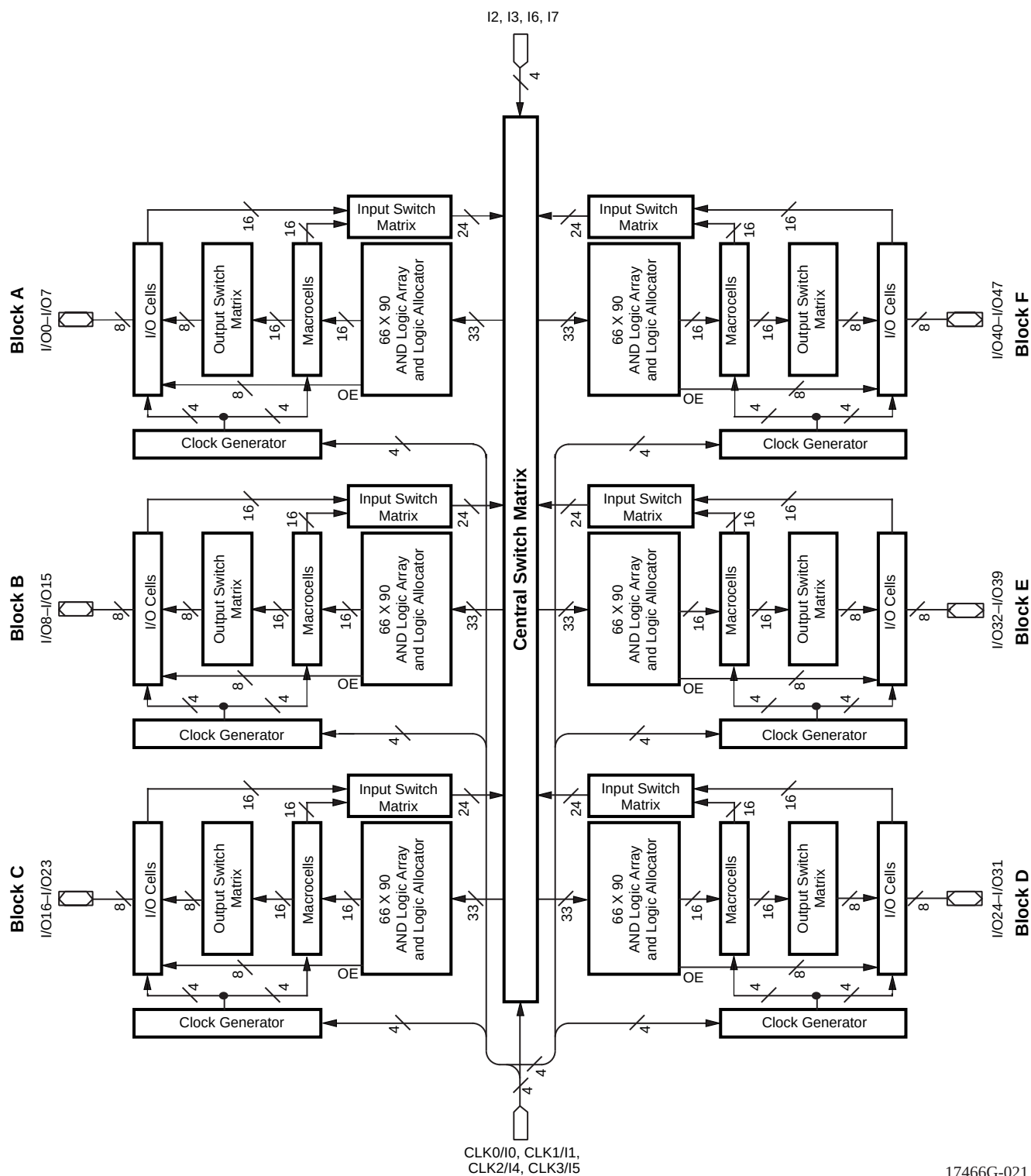
17466H-019

BLOCK DIAGRAM – M4A(3,5)-64/32



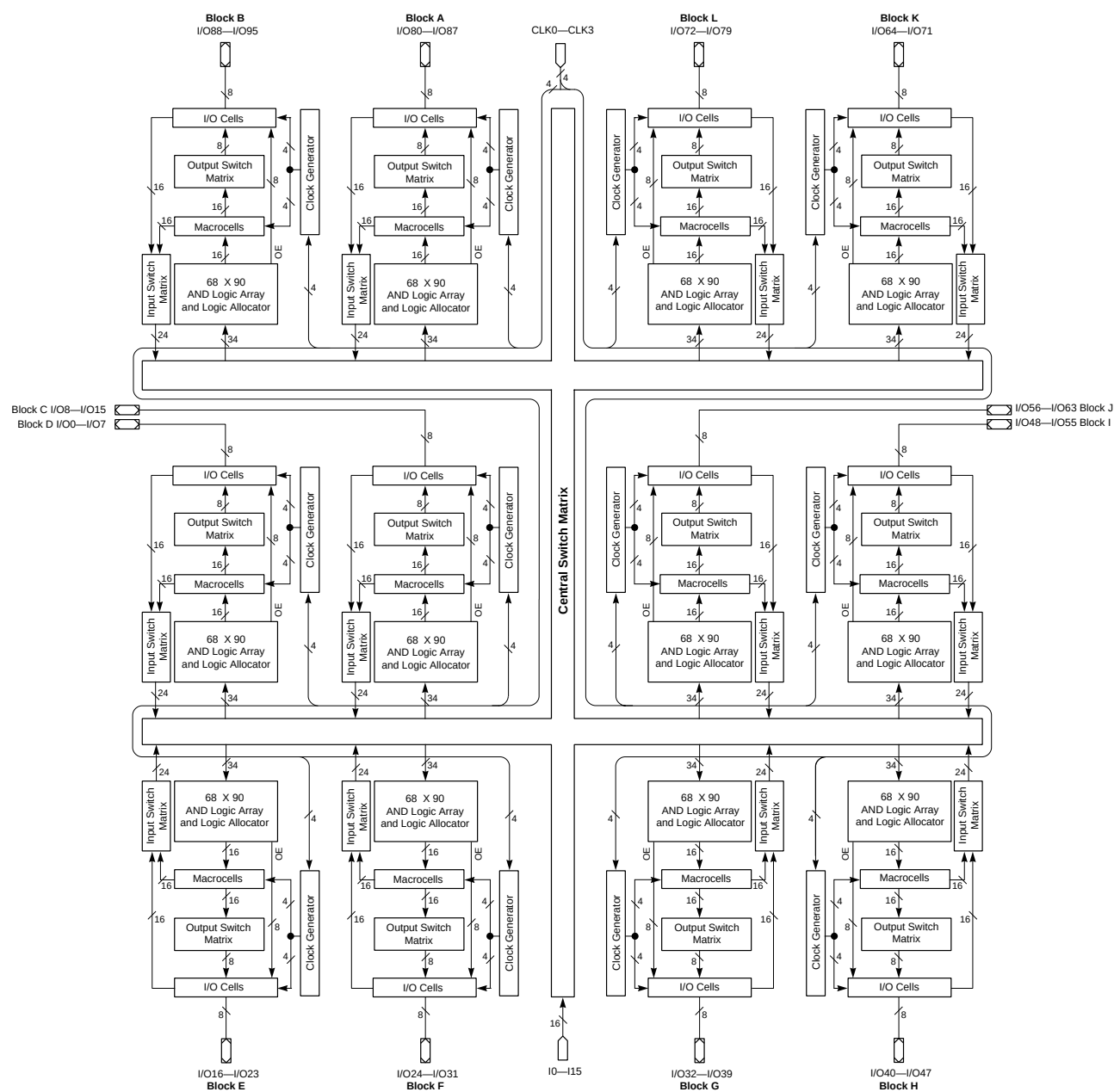
17466H-020

BLOCK DIAGRAM – M4A(3,5)-96/48



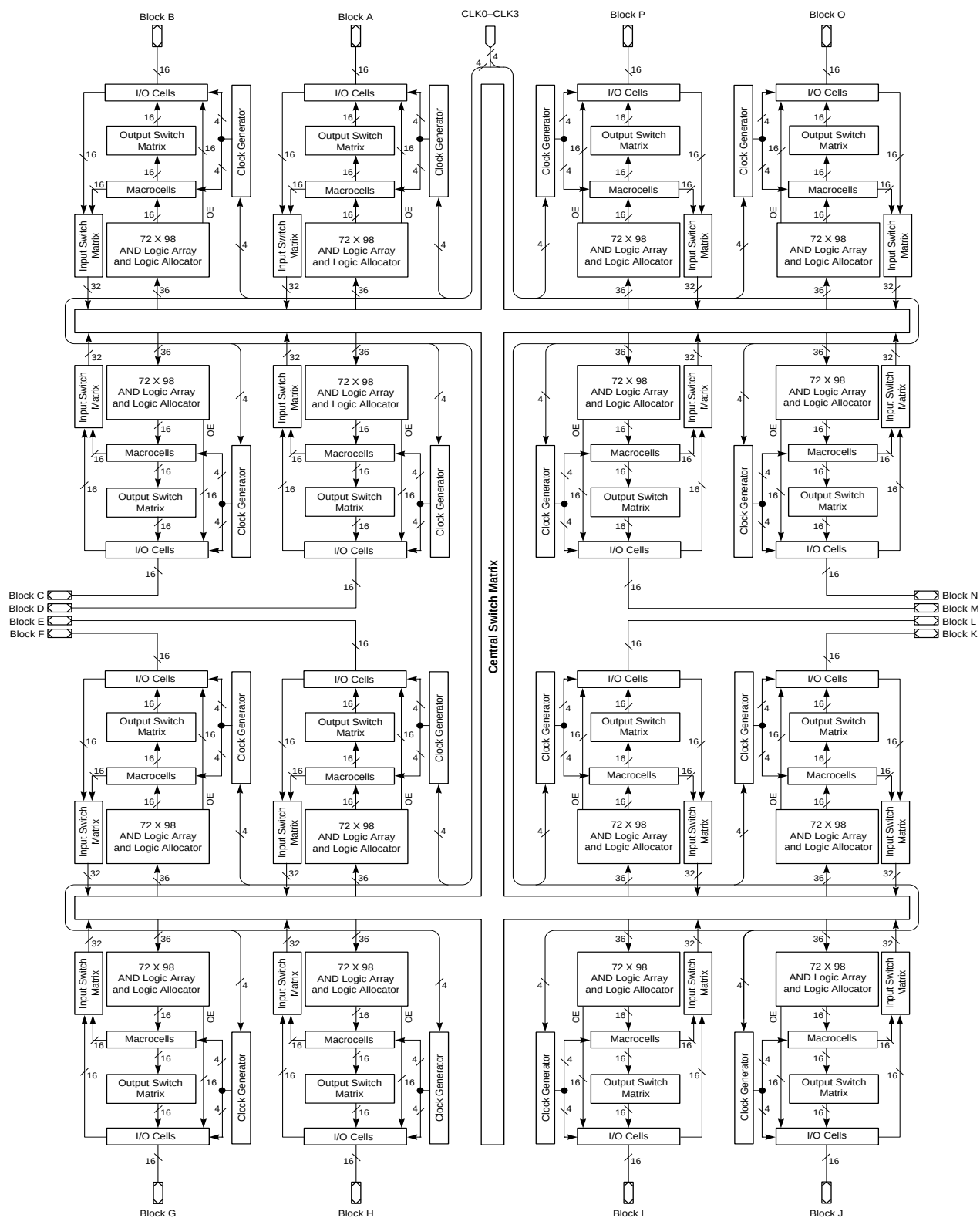
17466G-021

BLOCK DIAGRAM – M4A(3,5)-192/96



17466G-067

BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



17466G-050

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground -0.5 V to +7.0 V
 DC Input Voltage -0.5 V to $V_{CC} + 0.5$ V
 Static Discharge Voltage 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.50 V to +5.5 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
		$I_{OH} = -100$ μA , $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	$I_{OL} = 24$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25$ V, $V_{CC} = \text{Max}$ (Note 3)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0$ V, $V_{CC} = \text{Max}$ (Note 3)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5$ V, $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
4. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 $V_{OUT} = 0.5$ V has been chosen to avoid test problems caused by tester ground degradation.

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Input Register Delays with ZHT Option:																		
t _{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t _{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{PDIL} Z _i	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t _{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t _{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t _{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t _{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t _{SRI}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t _{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t _{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t _{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t _{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t _{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power.

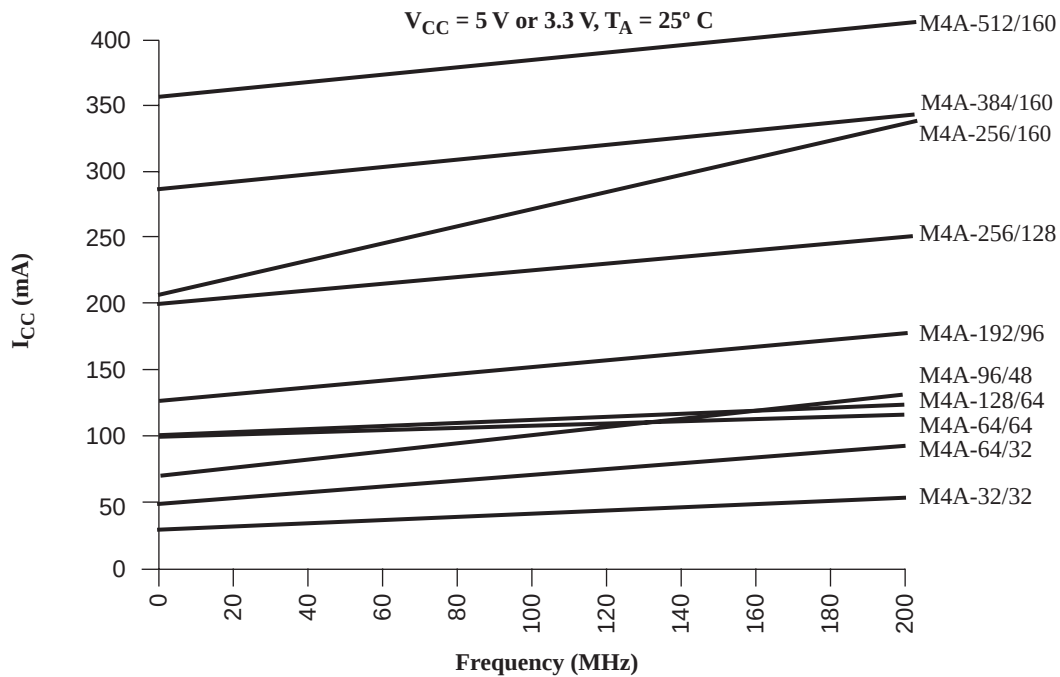


Figure 19. ispMACH 4A I_{CC} Curves at High Speed Mode

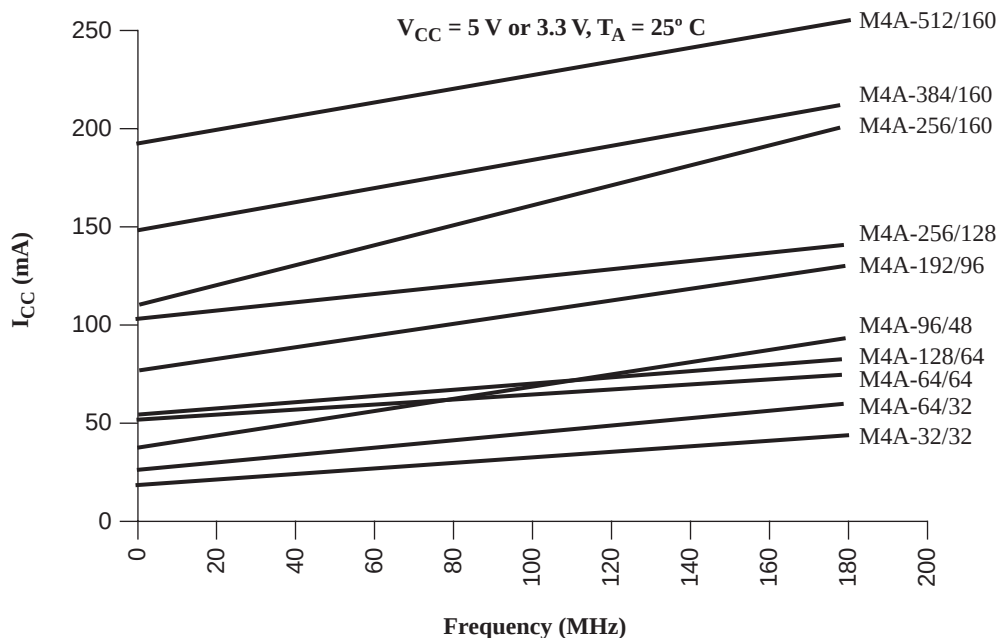
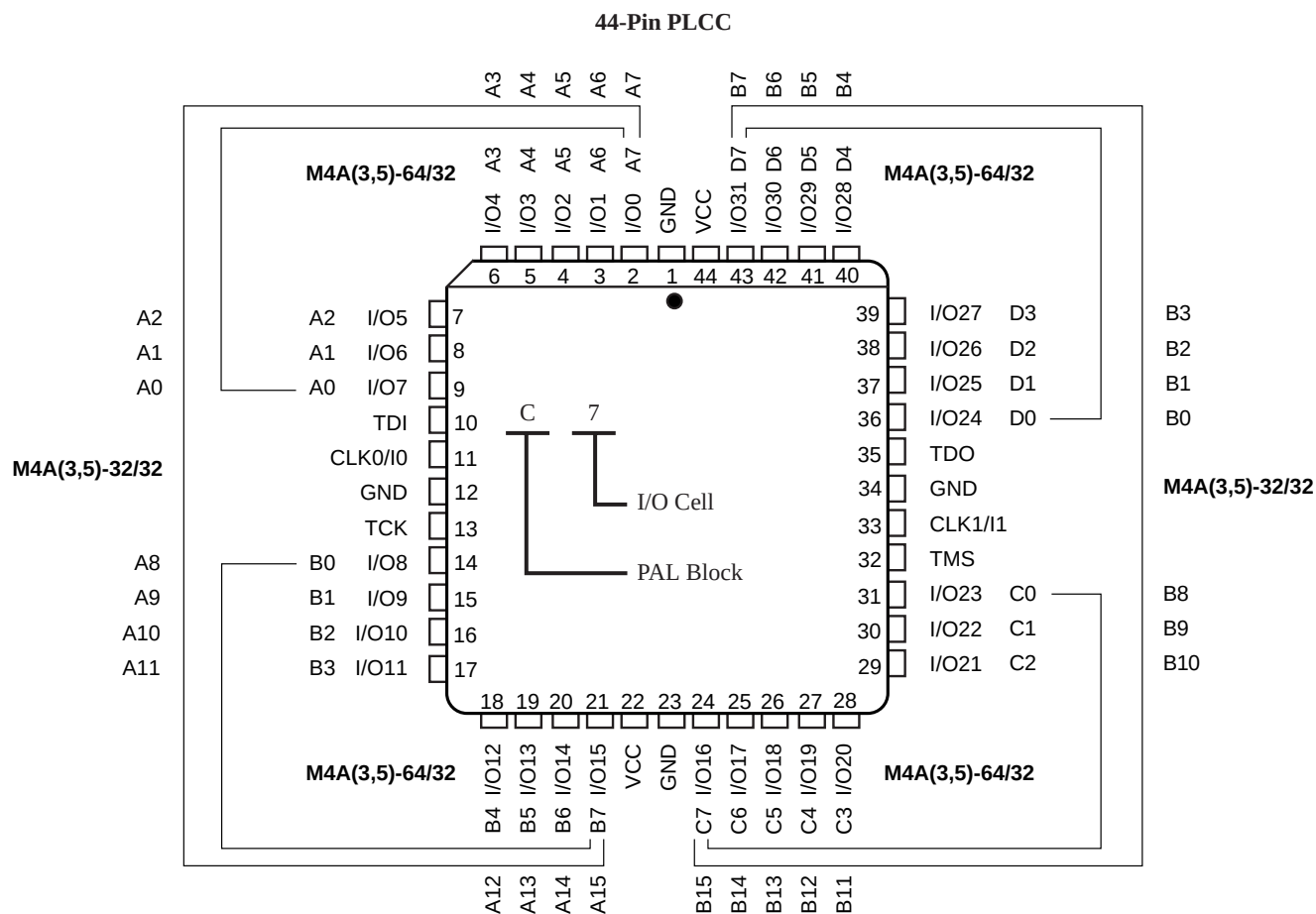


Figure 20. ispMACH 4A I_{CC} Curves at Low Power Mode

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

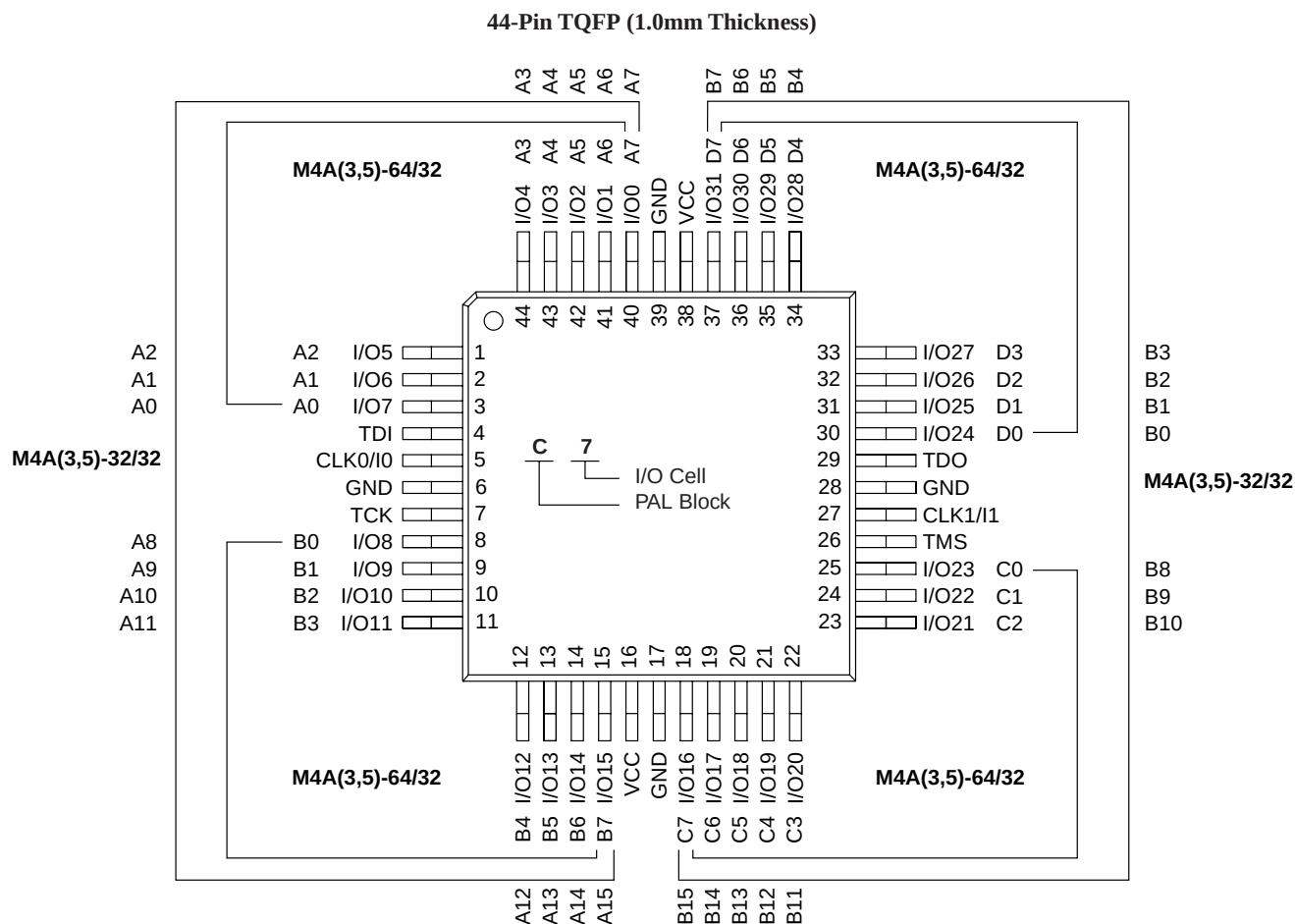
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

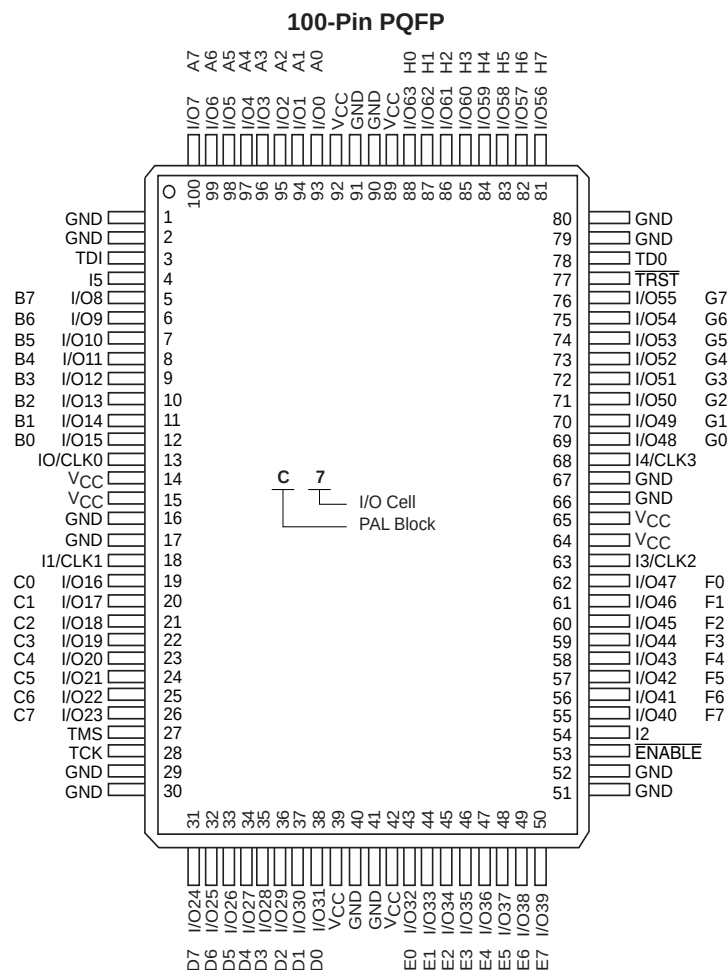
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

Top View



17466G-031

PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

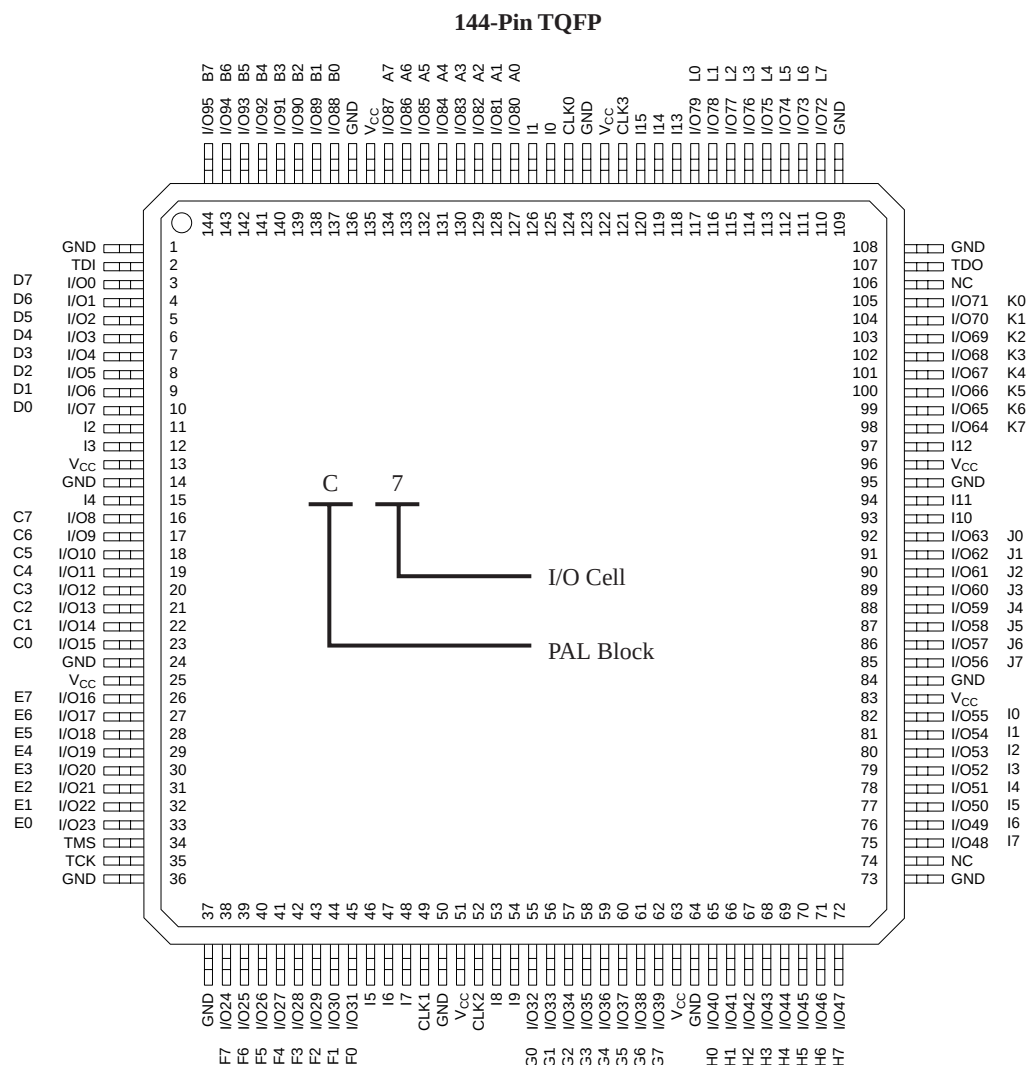
TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

144-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-192/96)

Top View



17466G-033

PIN DESIGNATIONS

- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out

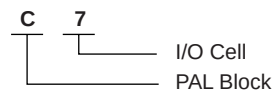
144-BALL FPBGA CONNECTION DIAGRAM (M4A3-192/96)

Bottom View

144-Ball fpBGA													
	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O72 L7	I/O76 L3	I13	GBCLK3	I0	I/O82 A2	I/O86 A6	I/O88 B0	I/O93 B5	I/O95 B7	GND	A
B	GND	I/O73 L6	I/O77 L2	I/O79 L0	VCC	I1	I/O83 A3	I/O87 A7	I/O90 B2	I/O94 B6	I/O0 D7	TDI	B
C	GND	TD0	I/O74 L5	I14	GND	I/O80 A0	I/O84 A4	GND	I/O92 B4	I/O1 D6	I/O4 D3	I/O3 D4	C
D	I/O67 K4	I/O69 K2	I/O71 K0	I/O75 L4	GBCLK0	I/O81 A1	VCC	I/O91 B3	I/O2 D5	I2	I/O6 D1	I/O7 D0	D
E	I12	I/O64 K7	I/O66 K5	I/O70 K1	I/O78 L1	I/O85 A5	I/O89 B1	I/O5 D2	I/O8 C7	I4	GND	VCC	E
F	I10	I11	GND	I/O65 K6	I/O68 K3	I15	I3	GND	I/O12 C3	I/O11 C4	I/O10 C5	I/O9 C6	F
G	I/O60 J3	I/O61 J2	I/O62 J1	I/O63 J0	VCC	GND	I7	I/O20 E3	I/O17 E6	I/O15 C0	I/O14 C1	I/O13 C2	G
H	I/O56 J7	I/O57 J6	I/O58 J5	I/O59 J4	I/O53 I2	I/O41 H1	I/O37 G5	I/O30 F1	I/O22 E1	I/O18 E5	I/O16 E7	VCC	H
J	I/O55 I0	I/O54 I1	VCC	I/O50 I5	I/O43 H3	VCC	I/O33 G1	GBCLK2	I/O27 F4	I/O23 E0	I/O21 E2	I/O19 E4	J
K	I/O51 I4	I/O52 I3	I/O49 I6	I/O44 H4	GND	I/O36 G4	I/O32 G0	VCC	I6	I/O26 F5	TCK	TMS	K
L	GND	I/O48 I7	I/O46 H6	I/O42 H2	I/O39 G7	I/O35 G3	I9	GND	I/O31 F0	I/O29 F2	I/O25 F6	GND	L
M	GND	I/O47 H7	I/O45 H5	I/O40 H0	I/O38 G6	I/O34 G2	I8	GBCLK1	I5	I/O28 F3	I/O24 F7	GND	M
	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TD0 = Test Data Out



m4a3.192.96_144bga

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-256/192)

Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O167 N15	I/O181 O13	I/O180 O12	I/O177 O9	I/O174 O6	I/O172 O4	I/O191 P14	I/O186 P4	I/O1 A2	I/O3 A6	GCLK0	I/O9 B1	I/O13 B5	I/O15 B7	I/O18 B10	I/O20 B12	A
B	I/O165 N13	I/O166 N14	I/O182 O14	I/O179 O11	I/O175 O7	I/O173 O5	I/O168 O0	I/O187 P6	I/O0 A0	I/O5 A10	I/O7 A14	I/O10 B2	I/O16 B8	I/O19 B11	I/O21 B13	NC	B
C	I/O163 N11	I/O164 N12	NC	I/O183 O15	I/O178 O10	I/O170 O2	I/O171 O3	I/O189 P10	I/O184 P0	I/O6 A12	I/O12 B4	I/O14 B6	I/O23 B15	I/O22 B14	TDI	I/O39 C15	C
D	I/O158 N6	I/O159 N7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O17 B9	I/O38 C14	I/O37 C13	D
E	I/O156 N4	NC	I/O162 N10	VCC	I/O160 N8	I/O161 N9	I/O190 P12	GCLK3	I/O188 P8	I/O2 A4	I/O8 B0	NC	GND	I/O36 C12	I/O35 C11	I/O31 C7	E
F	I/O152 N0	I/O157 N5	I/O155 N3	GND	I/O154 N2	I/O153 N1	I/O176 O8	I/O169 O1	I/O185 P2	I/O4 A8	I/O11 B3	I/O34 C10	VCC	I/O32 C8	I/O30 C6	I/O29 C5	F
G	I/O147 M6	I/O150 M12	I/O149 M10	VCC	I/O148 M8	I/O151 M14	VCC	GND	GND	VCC	I/O33 C9	I/O28 C4	GND	I/O26 C2	I/O25 C1	I/O47 D14	G
H	I/O144 M0	I/O146 M4	I/O145 OM2	GND	I/O136 L0	I/O137 L2	GND	VCC	VCC	GND	I/O27 C3	I/O24 C0	VCC	I/O44 D8	I/O43 D6	I/O42 D4	H
J	I/O138 L4	I/O139 L6	I/O140 L8	GND	I/O142 L12	I/O141 L10	GND	VCC	VCC	GND	I/O46 D12	I/O45 D10	GND	I/O49 E2	I/O48 E0	I/O50 E4	J
K	I/O143 L14	I/O120 K0	I/O121 K1	VCC	I/O123 K3	I/O122 K2	VCC	GND	GND	VCC	I/O41 D2	I/O40 D0	VCC	I/O55 E14	I/O54 E12	I/O56 F0	K
L	I/O124 K4	I/O125 K5	I/O127 K7	GND	I/O130 K10	I/O126 K6	I/O98 I4	I/O91 H6	I/O75 G3	I/O77 G5	I/O52 E8	I/O51 E6	GND	I/O59 F3	I/O60 F4	I/O57 F1	L
M	I/O128 K8	I/O129 K9	I/O131 K11	GND	I/O107 J3	I/O105 J1	I/O100 I8	I/O90 H4	I/O74 G2	I/O80 G8	I/O83 G11	I/O53 E10	VCC	I/O68 F12	I/O63 F7	I/O58 F2	M
N	I/O132 K12	I/O133 K13	I/O135 K15	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O64 F8	I/O61 F5	N
P	I/O134 K14	I/O117 J13	I/O118 J14	I/O119 J15	I/O108 J4	I/O106 J2	I/O101 I10	I/O89 H2	I/O93 H10	I/O94 H12	I/O79 G7	I/O84 G12	I/O87 G15	TMS	I/O65 F9	I/O62 F6	P
R	I/O116 J12	I/O115 J11	I/O112 J8	I/O111 J7	I/O104 J0	I/O102 I12	I/O99 I6	I/O96 I0	I/O92 H8	I/O72 G0	I/O76 G4	I/O81 G9	I/O85 G13	I/O71 F15	I/O67 F11	I/O66 F10	R
T	I/O114 J10	I/O113 J9	I/O110 J6	I/O109 J5	I/O103 I14	GCLK2	I/O97 I2	I/O88 H0	GCLK1	I/O95 H14	I/O73 G1	I/O78 G6	I/O82 G10	I/O86 G14	I/O70 F14	I/O69 F13	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



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256-BALL BGA CONNECTION DIAGRAM - (M4A3-384/192)

Bottom View

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1		
A	GND	I/O11 FX7	GND	I/O44 FX6	I/O58 CX6	GND	I/O70 CX2	I/O76 DX6	GND	GND	GND	GND	I/O108 AX5	I/O116 BX0	GND	I/O128 BX7	I/O134 O3	GND	GND	GND	A	
B	GND	I/O12 GX7	I/O28 FX5	I/O45 FX3	I/O59 CX7	I/O64 CX5	I/O71 CX3	I/O77 DX7	I/O84 DX5	I/O90 DX2	I/O96 AX0	I/O102 AX3	I/O109 AX6	I/O117 BX1	I/O122 BX4	I/O129 BX6	I/O135 O4	I/O148 O6	I/O164 O7	GND	B	
C	I/O0 GX6	I/O13 GX5	VCC	I/O46 FX4	I/O60 FX2	I/O65 FX1	I/O72 CX4	I/O78 CX0	I/O85 DX4	I/O91 DX1	I/O97 AX1	I/O103 AX4	I/O110 BX2	I/O118 BX5	I/O123 O0	I/O130 O1	I/O136 O5	VCC	I/O165 N7	I/O181 N6	C	
D	I/O1 EX7	I/O14 GX3	I/O29 GX4	VCC	VCC	I/O66 FX0	VCC	I/O79 CX1	I/O86 DX3	I/O92 DX0	I/O98 AX2	I/O104 AX7	I/O111 B3X	VCC	I/O124 O2	VCC	VCC	I/O149 N4	I/O166 N5	I/O182 P7	D	
E	I/O2 EX0	I/O15 GX0	I/O30 GX1	TDI	PIN DESIGNATIONS CLK = Clock GND = Ground I = Input I/O = Input/Output N/C = No Connect VCC = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out C7 I/O Cell PAL Block													TDO	I/O150 N2	I/O167 N3	I/O183 P6	E
F	GND	I/O16 EX1	I/O31 EX6	I/O47 GX2														I/O137 N1	I/O151 N0	I/O168 P5	GND	F
G	I/O3 HX6	I/O17 EX4	I/O32 EX5	VCC														VCC	I/O152 P4	I/O169 P3	I/O184 M7	G
H	GND	I/O18 HX5	I/O33 EX2	I/O48 EX3														I/O138 P2	I/O153 P1	I/O170 P0	GND	H
J	I/O4 HX0	I/O19 HX1	I/O34 HX4	I/O49 HX7														I/O139 M6	I/O154 M5	I/O171 M4	I/O185 M3	J
K	GND	CLK3	I/O35 HX2	I/O50 HX3														I/O140 M0	I/O155 M1	CLK2	I/O186 M2	K
L	I/O5 A2	CLK0	I/O36 A0	I/O51 A1														I/O141 L3	I/O156 L4	CLK1	GND	L
M	I/O6 A4	I/O20 A3	I/O37 A5	I/O52 A6														I/O142 L6	I/O157 L5	I/O172 L0	I/O187 L1	M
N	GND	I/O21 A7	I/O38 D0	I/O53 D1														I/O143 I5	I/O158 I0	I/O173 L7	GND	N
P	I/O7 D2	I/O22 D3	I/O39 D4	VCC	VCC	I/O159 I4	I/O174 I1	I/O188 L2	P													
R	GND	I/O23 D5	I/O40 D6	I/O54 D7	I/O144 K5	I/O160 K0	I/O175 I3	GND	R													
T	I/O8 B3	I/O24 B0	I/O41 B7	TCK	TMS	I/O161 K4	I/O176 K1	I/O189 I2	T													
U	I/O9 B4	I/O25 B1	I/O42 B6	VCC	VCC	I/O67 C0	VCC	I/O80 F0	I/O87 E5	I/O93 E2	I/O99 H2	I/O105 H5	I/O112 G0	VCC	I/O125 J1	VCC	VCC	I/O162 K7	I/O177 K2	I/O190 I6	U	
V	I/O10 B5	I/O26 B2	VCC	I/O55 C5	I/O61 C2	I/O68 C1	I/O73 F4	I/O81 F1	I/O88 E4	I/O94 E1	I/O100 H1	I/O106 H4	I/O113 G1	I/O119 G4	I/O126 J0	I/O131 J2	I/O145 J5	VCC	I/O178 K3	I/O191 I7	V	
W	GND	I/O27 C7	I/O43 C6	I/O56 C3	I/O62 F7	I/O69 F5	I/O74 F3	I/O82 E7	I/O89 E3	I/O95 E0	I/O101 H0	I/O107 H3	I/O114 H7	I/O120 G3	I/O127 G5	I/O132 G7	I/O146 J4	I/O163 J6	I/O179 J7	GND	W	
Y	GND	GND	GND	I/O57 C4	I/O63 F6	GND	I/O75 F2	I/O83 E6	GND	GND	GND	GND	I/O115 H6	I/O121 G2	GND	I/O133 G6	I/O147 J3	GND	I/O180 K6	GND	Y	
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1		

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Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.